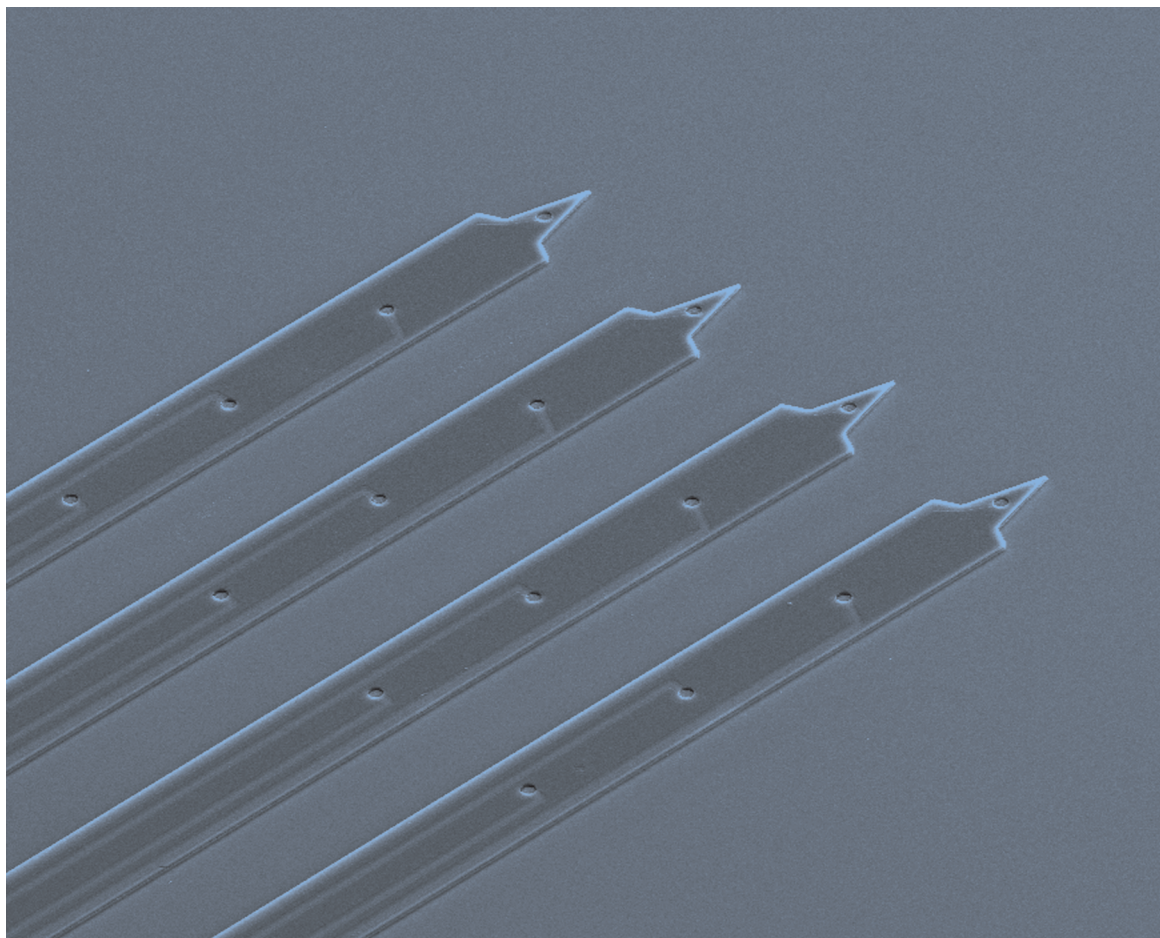




Development, characterization, and application of compliant intracortical implants

Kagithiri Srikantharajah

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